

REMARKS

Entry of the foregoing, reexamination and reconsideration of the subject matter identified in caption, as amended, pursuant to and consistent with 37 C.F.R. §1.112, and light of the remarks which follow are respectfully requested.

Claims 1-28 are pending in the application, claims 27 and 28 having been newly presented above. Support for the new claims can be found at least in original claims 1 and 2 and paragraph [0032].

By the foregoing amendments, claim 4 has been revised for antecedent basis purposes, and claims 6, 7, 21 and 22 have been revised for form.

Turning now to the Official Action, applicant notes with appreciation the indication of allowable subject matter with respect to claims 2-10 and 18-26.

Claims 1, 11, 14 and 15 stand rejected under 35 U.S.C. §103(a) as being unpatentable over *Morikawa* (U.S. Patent No. 6,132,107). In addition, claims 12, 13, 16 and 17 stand rejected under 35 U.S.C. §103(a) as being unpatentable over *Morikawa* in view of *Clark* (U.S. Patent No. 5,073,003). These rejections are respectfully traversed for at least the following reasons.

The present invention relates to optoelectronic packages and to methods for coupling optoelectronic packages. To connect together two sets of optical fibers or optical components, or an optical component and an optical fiber, it is required that the objects are properly aligned with one another. A number of methods and devices exist for connecting together sets of fibers. These methods and devices, however, do not provide for satisfactory alignment or require a relatively long time to do so. (See specification at § 0003-0004). Through the present invention, applicant has addressed the deficiencies in the existing methods and devices.

Independent claim 1, for example, sets forth an optoelectronic package comprising: a base chip, the chip comprising a base chip V-groove; a fiber array, the array comprising an array V-groove formed in a rear portion and a front portion of the array; a first wick stop disposed between the rear and front portions; and an optical fiber, having an angled endface, disposed in both V-grooves to substantially couple the chip and array. Independent claim 14 sets forth a method for coupling optoelectronic packages.

Based on a complete understanding of the present invention, it is respectfully submitted that *Morikawa* taken alone or in combination with *Clark* does not disclose or suggest each feature of applicant's invention.

Morikawa relates to a light-receiving module and a method for its fabrication.

Morikawa does not disclose or suggest each feature of the present invention. For example, *Morikawa* does not disclose or fairly suggest a fiber array comprising an array V-groove formed in a rear portion and a front portion of the array, and a first wick stop disposed between the rear and front portions. In this regard, the Official Action makes reference generally to Figures 3-8 and column 5, lines 1-13 of *Morikawa*. Review of those figures and cited text, however, reveal no teaching of a wick stop. As described in the specification, the wick stop functions to prevent glue (or another adhesive) which has been applied to the fiber on the rear portion of the array from flowing to the front portion of the array during assembly of the package. There is no remote suggestion of a wick stop as presently claimed.

Moreover, as correctly recognized by the Examiner, *Morikawa* "does not disclose an optical fiber having an angled endface as recited in claims 1 and 14" (see Official Action at pages 3-4). To address this feature, the Examiner summarily takes the position that "it would have been an obvious matter of design choice to make the optical fiber with and [sic] angled end face . . . (Official Action at page 4). Applicants respectfully disagree with the Examiner's position.

Morikawa in no way discloses or suggests an optical fiber having an angled endface to substantially couple the chip and array. Quite to the contrary, *Morikawa* discloses a reflector which is separate from the optical fiber for coupling light, and that document is noticeably silent with respect to alternative coupling techniques. There is simply no motivation absent applicant's own disclosure to have modified *Morikawa* in the manner suggested in the Official Action.

For at least the foregoing reasons, withdrawal of the §103(a) rejection based on *Morikawa* is in order.

Moreover, regarding the §103(a) rejection based on the combination of *Morikawa* and *Clark*, *Clark* cannot cure the deficiencies in the primary reference.

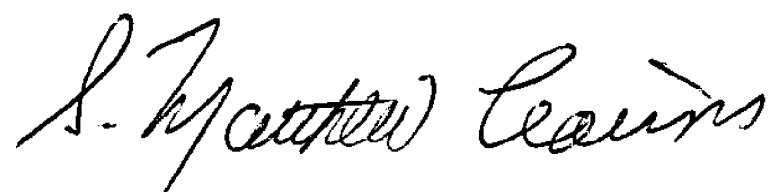
Clark is relied on in the Official Action for that document's alleged disclosure of a VCSEL and photodetector. *Clark*, however, fails to disclose or suggest a wick stop as presently claimed, or an optical fiber having an angled endface to substantially couple the chip and array. Thus, even if combined in the manner suggested in the Official Action, the proposed combination of *Morikawa* and *Clark* would not result in the present invention.

Accordingly, withdrawal of these rejections is respectfully requested.

From the foregoing, further and favorable action in the form of a Notice of Allowance is believed to be next in order, and such action is earnestly solicited.

If there are any questions concerning this paper or the application in general, the Examiner is invited to telephone the undersigned at her earliest convenience.

Respectfully submitted,



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